

#### **Description**

The HXY100N03DF uses advanced trench technology

to provide excellent R<sub>DS(ON)</sub>, low gate charge and

operation with gate voltages as low as 4.5V. This

device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

 $V_{DS} = 30V I_{D} = 100A$ 

 $R_{DS(ON)} < 5.5 \,\text{m}\Omega$  @  $V_{GS}=10V$ 

#### **Application**

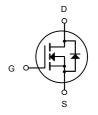
**Battery protection** 

Load switch

Uninterruptible power supply



DFN3X3-8L



N-Channel MOSFET

### **Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
HXY100N03DF	DFN3X3-8L	100N03 XXX YYYY	5000

#### Absolute Maximum Ratings (TC=25°C unless otherwise specified)

Symbol	Parameter	Rating	Units
V <sub>D</sub> s	Drain-Source Voltage	30	V
V <sub>G</sub> s	Gate-Source Voltage	±20	V
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	100	Α
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	70	Α
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	30	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	25	Α
Ідм	Pulsed Drain Current <sup>2</sup>	192	А
EAS	Single Pulse Avalanche Energy <sup>3</sup>	144.7	mJ
las	Avalanche Current	53.8	Α
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation <sup>4</sup>	62.5	W
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	4.5	W
Тэтс	Storage Temperature Range	-55 to 150	°C
Tu	Operating Junction Temperature Range	-55 to 150	°C
Reja	Thermal Resistance Junction-ambient <sup>1</sup> 62		°C/W
Rejc	Thermal Resistance Junction-Case <sup>1</sup>	2.4	°C/W



# Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V
∆BVbss/∆Tj	BVDSS Temperature Coefficient	Reference to 25°C ,		0.0213		V/°C
		V <sub>GS</sub> =10V , I <sub>D</sub> =30A		4	5.5	
RDS(ON)	Static Drain-Source On- Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		5.2	6	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage		1.0		2.5	V
$\triangle V_{\text{GS(th)}}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250$ uA		-5.8		mV/°C
		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	
IDSS	Drain-Source Leakage Current  VDS=24V, VGS=0V, TJ=55°C				5	uA
Igss	Gate-Source Leakage Current	$V_{GS}=\pm 20V$ , $V_{DS}=0V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =30A		26.5		S
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.4		Ω
Qg	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V ,		31.6		
Qgs	Gate-Source Charge			8.6		nC
$Q_{gd}$	Gate-Drain Charge	10-13A		11.7		
T <sub>d(on)</sub>	Turn-On Delay Time			9		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		19		
Td(off)	Turn-Off Delay Time			58		ns
T <sub>f</sub>	Fall Time	_I <sub>D</sub> =15A		15.2		
Ciss	Input Capacitance			3075		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V ,		400		pF
Crss	Reverse Transfer Capacitance	f=1MHz		315		
ls	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force			100	Α
Іѕм	Pulsed Source Current <sup>2,6</sup>	Current			192	Α
	1	1	1			V

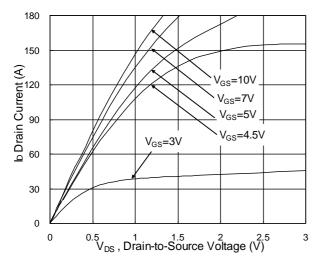
#### Diode Characteristics

#### Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq 300 us$  , duty cycle  $\leqq 2\%$
- 3 .The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25\text{V}, V_{\text{GS}}\text{=}10\text{V}, L\text{=}0.1\text{mH}, I_{\text{AS}}\text{=}34\text{A}$
- 4. The power dissipation is limited by 150 °C junction temperature
- 5 .The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



### **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

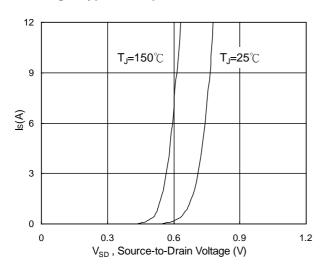


Fig.3 Forward Characteristics of Reverse

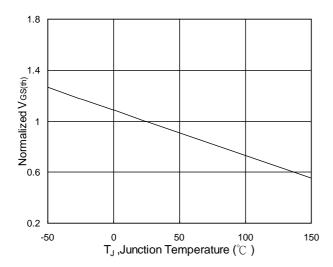


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$ 

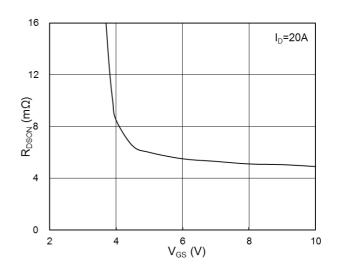


Fig.2 On-Resistance vs. G-S Voltage

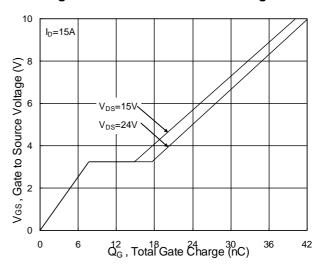


Fig.4 Gate-Charge Characteristics

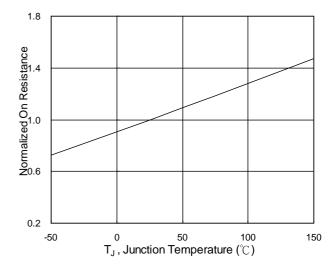
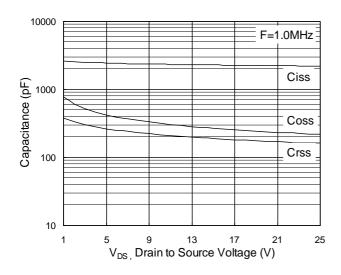


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



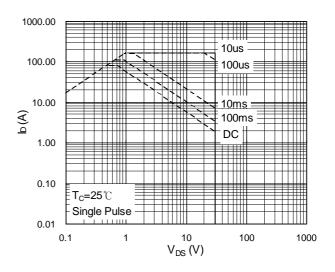


Fig.7 Capacitance

Fig.8 Safe Operating Area

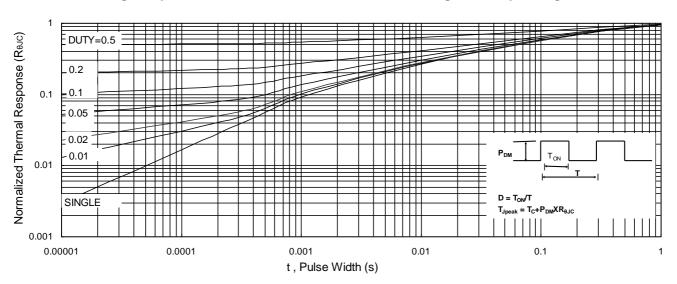


Fig.9 Normalized Maximum Transient Thermal Impedance

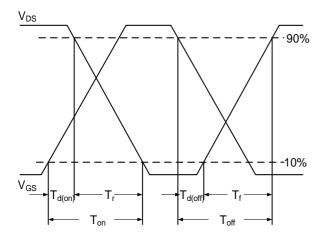


Fig.10 Switching Time Waveform

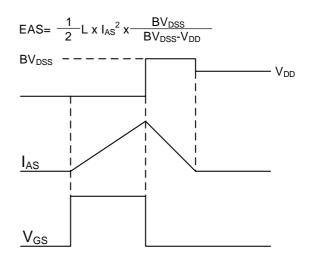
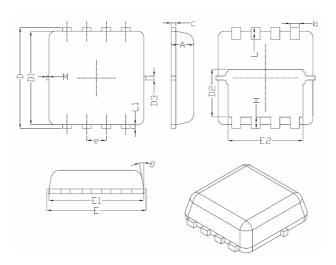


Fig.11 Unclamped Inductive Switching Waveform

# **DFN3X3-8L Package Information**



Symbol	Dimensions In Millimeters			
	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10 <sup>°</sup>	12 <sup>°</sup>	

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